

## Re-Configurable 6 Output PECL TCXO

- Fixed & Re-Configurable Multi-Frequency Oscillator
- Intuitive software and PC interface
- Easily update system
- Industry-standard packaging saves on board space
- Mult. outputs 1 pkg vs. mult. osc & assoc. comp.
- Differential PECL Output
- Performs well under all conditions

## Applications

- High-end multimedia
- Communications
- Industrial
- A/D converters
- Consumer Applications
- New and innovative products
- Temperature-sensitive applications

Series

CCT6RE



Part Numbering Example: CCT6RE 1A 200.0 - 150.0 / 125.0 / 100.0 / 12.0

CCT6RE	1A	200	150	125	100	12
SERIES	PACKAGE STYLE	FREQUENCY P/P-	FREQUENCY A	FREQUENCY B	FREQUENCY C	FREQUENCY R
1A=14 pin dip 9=9.6x11.4 SMD	100-400 MHz PECL	0.2 - 200 MHz	0.2 - 200 MHz	0.2 - 200 MHz	0.2 - 200 MHz	

## Specifications:

Specifications:	Min	Typ	Max	Unit
<b>Frequency Range:</b>				
Output PECL +	100		400	MHz
Output PECL -	100		400	MHz
Output A CMOS	0.2		200	MHz
Output B CMOS	0.2		200	MHz
Output C CMOS	0.2		200	MHz
Output R Fixed	0.2	12		MHz
<b>Available Stability Options:</b>	-2.5		2.5	ppm
<b>Supply Voltage:</b>	3.135	3.3	3.465	V
<b>Operating Temperature Range Options:</b>	-40		85	°C
<b>Storage Temperature:</b>	-55		125	°C
<b>Duty Cycle:</b>	40 45		60 55	% %
<b>Start-Up Time:</b>		3	10	ms
<b>Aging (PPM/1st Year):</b> Ta=25C, Vdd=3.3V			±1	ppm
<b>Static Discharge Voltage</b> Mil-Std 883, method 3015	2000			V
<b>Output Load:</b> * CMOS, < 40 MHz CMOS, ≥ 40 MHz			30 15	pF pF
<b>Output Level:</b>	PECL/CMOS			
<b>Packaging:</b>	25 / Tube Tape & Reel			14 pin SMD

Notes: Recommended .01 µF bypass capacitor from Vcc to GND. Capacitor should be as close to oscillator as possible.  
\* LV PECL outputs require an external termination network

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Specifications subject to change without notice. Check website for latest updates



## Electrical Characteristics

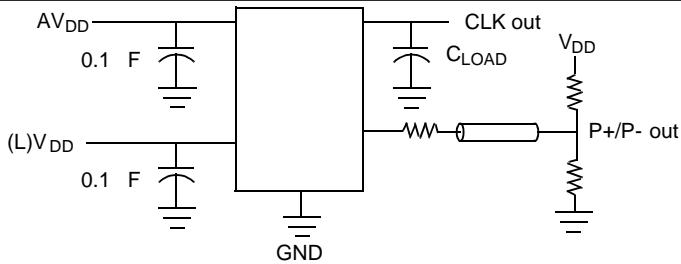
DESCRIPTION		CONDITIONS	MIN	TYP	MAX	UNIT
IoH	Output High Current	$V_{oh} = (L)V_{dd} - 0.5$ , $(L)V_{dd} = 3.3$ V	12	24		mA
IoL	Output Low Current	$V_{ol} = .5$ , $(L)V_{dd} = 3.3$ V	12	24		mA
Vih	High Level Input Voltage	CMOS levels, % of Vdd	0.7			V
Vil	Low-Level Input Voltage	CMOS levels, % of Vdd			0.3	V
Iih	Input High Current	$V_{in} = AV_{dd} - 0.3$ V		<1	10	$\mu$ A
Iil	Input Low Current	$V_{in} = + 0.3$ V		<1	10	$\mu$ A
IoZ	Output Leakage Current	tri-state outputs			10	$\mu$ A
Idd	Total Power Supply Current	Example 1: 1 PECL output @155.52 MHz 1 CMOS output @19.44 MHz 1 CMOS output @38.88 MHz 1 CMOS output @77.76 MHz 1 CMOS output @12 MHz Example 2: 1 PECL output @400 MHz 1 CMOS output @106.25 MHz 1 CMOS output @200 MHz 1 CMOS output @100 MHz 1 CMOS output @12 MHz		29		mA
Idds	Shutdown Power Supply Curr	Shutdown active		59		mA
Idds	Shutdown Power Supply Curr	Shutdown active		5	20	$\mu$ A

## Output Clock Switching Characteristics

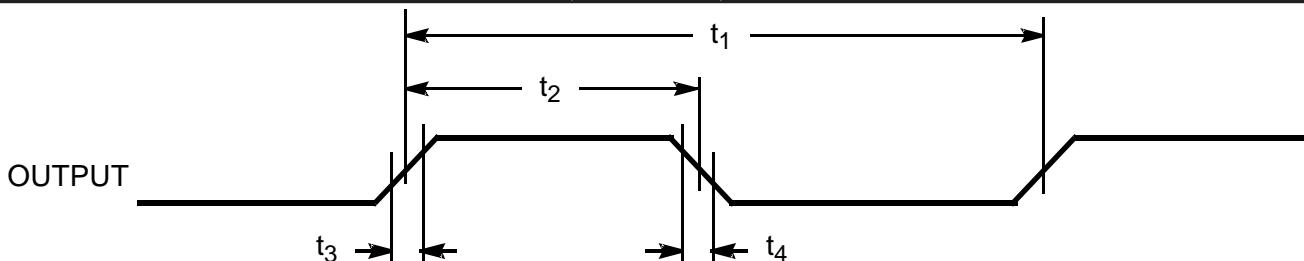
DESCRIPTION		CONDITIONS	MIN	TYP	MAX	UNIT
1/t1	Output Frequency	Clock output limit, CMOS, Commercial Clock output limit, PECL, Commercial	0.2 100		200 400	MHz MHz
t3	Rising Edge Slew Rate	Output clock rise time, 20% – 80% Vdd	0.75	1.4		nS
t4	Falling Edge Slew Rate	Output clock fall time, 20% – 80% Vdd	0.75	1.4		nS
t5	Output tri-state timing after SD/OE switches	Time for output to enter/leave tri-state mode		150	300	nS
t6	Clock Jitter measured at Vdd/2	Peak-to-Peak period jitter, CLK outputs		200		pS
v7	P+/P- Crossing Point	Crossing point ref. to Vdd/2, bal res. net	-0.2	0	0.2	V
	Frequency Switch Time	Change time		2	4	ms



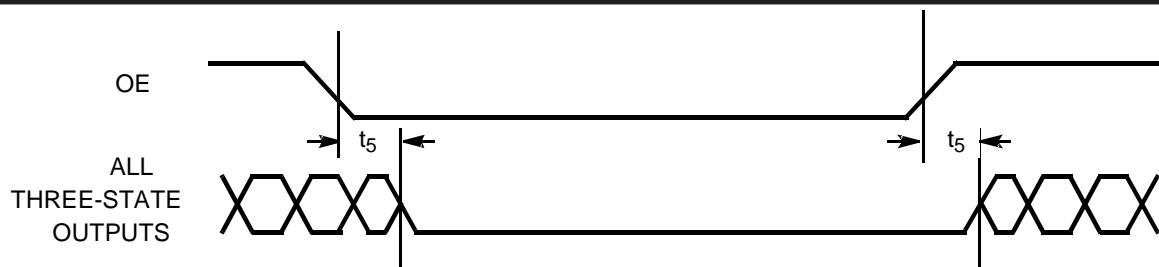
## TEST CIRCUIT



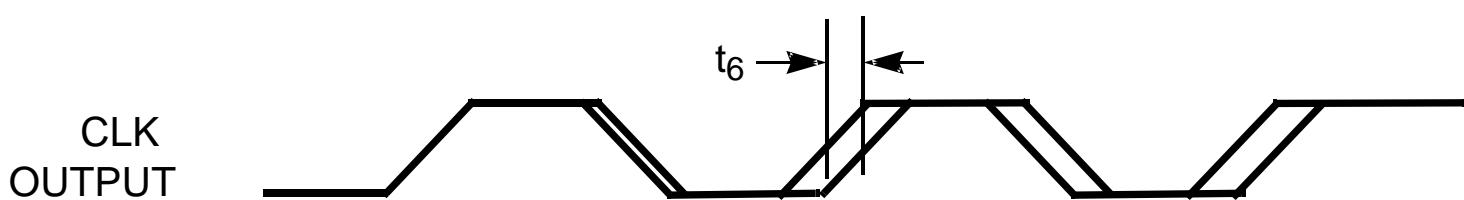
## ALL OUTPUTS, DUTY CYCLE, RISE/FALL TIME



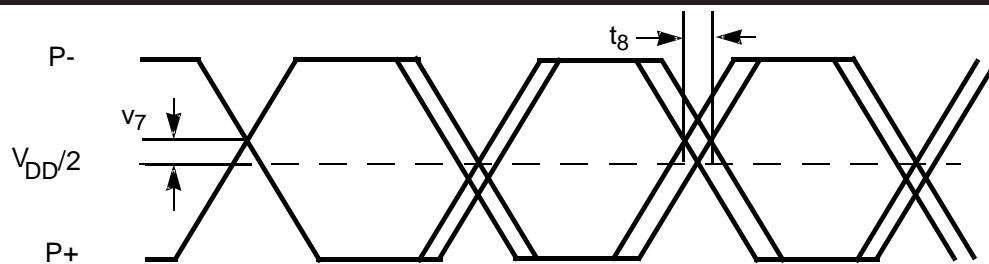
## OUTPUT TRI-STATE TIMING



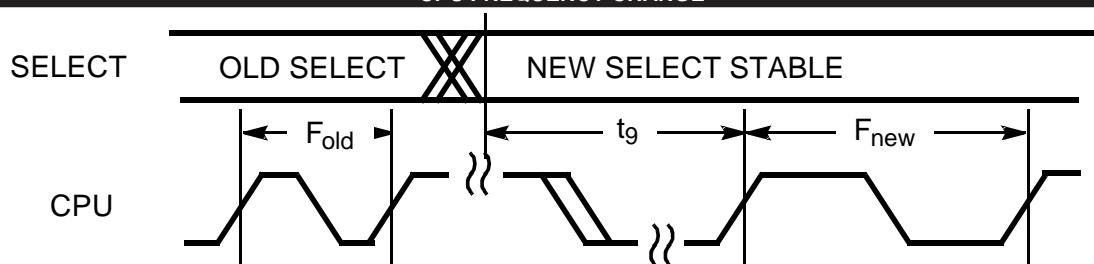
## CLK OUTPUT JITTER



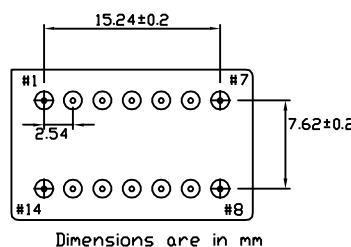
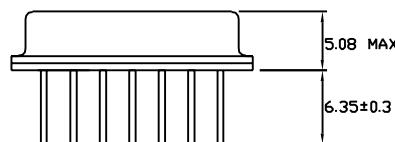
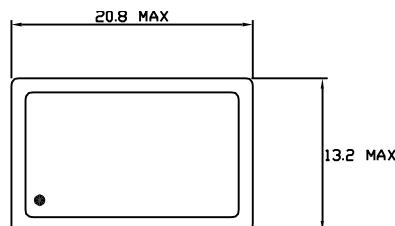
## P+/P- CROSSING POINT AND JITTER



## CPU FREQUENCY CHANGE



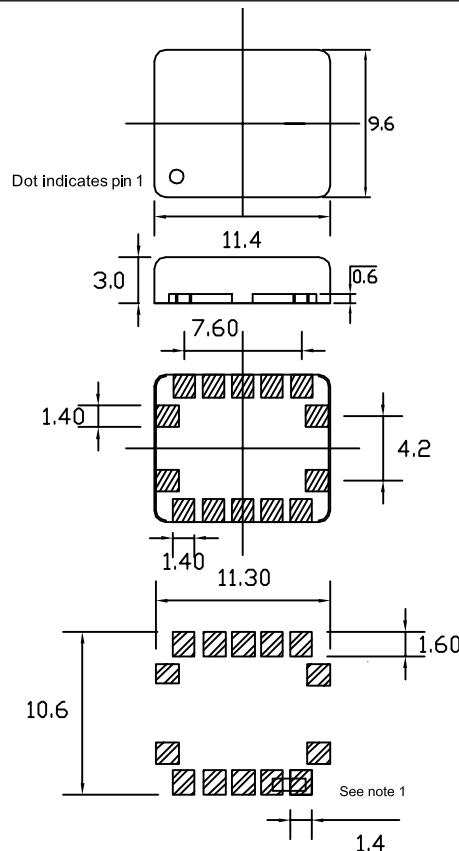
## DIP



**PIN FUNCTION**

PIN 1 OE (CONNECT TO VDD)  
PIN 2 SUSPEND (CONNECT TO GND)  
PIN 3 VDD  
PIN 4 CLK C OUTPUT  
PIN 5 CONNECT TO PIN 6  
PIN 6 CONNECT TO PIN 5  
PIN 7 GND  
PIN 8 12 MHz REF CLOCK OUTPUT  
PIN 9 PECL - OUTPUT  
PIN10 PECL + OUTPUT  
PIN 11 SDAT  
PIN 12 SCLK  
PIN 13 CLK A OUTPUT  
PIN 14 CLK B OUTPUT

## SMD



**PIN FUNCTION**

PIN 1 FACTORY USE (MAKE NO CONNECTION)  
PIN 2 OE  
PIN 3 VDD  
PIN 4 CLK C OUTPUT  
PIN 5 CONNECT TO PIN 6  
PIN 6 CONNECT TO PIN 5  
PIN 7 GND  
PIN 8 12 MHz REF CLOCK OUTPUT  
PIN 9 PECL - OUTPUT  
PIN10 PECL + OUTPUT  
PIN 11 SCLK  
PIN 12 SDAT  
PIN 13 CLK A OUTPUT  
PIN 14 CLK B OUTPUT

Dimensions in mm  
Recommended solder pad layout  
Note1:  
For proper operation pin 5 must be connected to pin 6



## Flash Programmability:

Non-Volatile programming enables easy customization, ultrafast turnaround, performance tweaking, design timing margin testing, inventory control, lower part count, and more secure product supply. In addition, any part in the family can also be programmed multiple times, which reduces programming errors and provides an easy upgrade path for existing designs.

## Feature of the I<sup>2</sup>C-bus:

- Only two bus lines are required; a serial data line (SDA) and a serial clock line (SCL)
- Each device connected to the bus is software addressable by a unique address and simple master/slave relationship exist at all times; master can operate as a master-transmitter or as master-receivers
- It's a true multi-master bus including collision detection and arbitration to prevent data corruption if two or more master simultaneously initiate data transfer
- Serial 8-bit oriented, bidirectional data transfers can be made at up to 100 Kbit/s in the standard mode, up to 400 kbit/s in the fast-mode, or up to 3.4 Mbit/s in the High-speed mode

## Designer Benefits:

I<sup>2</sup>C bus compatible In Circuit Reconfigurable Oscillator “ICRO” allow a system design to rapidly progress directly from a functional block diagram to a prototype. Moreover, since they ‘clip’ directly onto the I<sup>2</sup>C bus without any additional external interfacing, they allow a prototype system to be modified or upgraded simply by ‘clipping’ or ‘unclipping’ ICRO to or from the bus.

Here are some of the feature of I<sup>2</sup>C- bus compatible ICRO which are particularly attractive to designer

- Functional blocks on the block diagram correspond with the actual ICRO designs proceed rapidly from block diagram to final schematic
- No need to design bus interfaces because the I<sup>2</sup>C-bus interface is already integrated on the ICRO
- Integrated addressing and data-transfer protocol allow systems to be completely software-defined
- The same ICRO types can often be used in many different applications
- Design-time reduces as designers quickly become familiar with the frequently used functional book represented by I<sup>2</sup>C-bus compatible and ICRO
- ICRO can be added to or remove from system without affecting any other circuits on the bus

In addition to these advantages, the CMOS ICRO in the I<sup>2</sup>C-bus compatible range offer designers special feature which are particularly attractive for portable equipment and battery-backed systems.

## They All Have:

- Extremely low current consumption
- High Noise immunity
- Wide operating temperature range

## Manufacturer Benefits

I<sup>2</sup>C-bus compatible ICRO don't only assist designer, they also give a wider range of benefits to the equipment manufacturer because:

- The simple 2-wire serial I<sup>2</sup>C bus minimizes interconnections so ICRO have fewer pins and there are not so many PCB tracks; result- smaller and less expensive PCBs
- The completely integrated I<sup>2</sup>C-bus protocol eliminates the need for address decoders and other ‘glue logic’
- The multi-master capability of the I<sup>2</sup>C-bus allows rapid testing and alignment of end-user equipment via external connections to an assembly line
- I<sup>2</sup>C-bus handbook, I<sup>2</sup>C Website: [www.semiconductors.philips.com/I2C](http://www.semiconductors.philips.com/I2C)

